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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	ARM® Cortex®-M4F
Core Size	32-Bit Single-Core
Speed	160MHz
Connectivity	CANbus, CSIO, I ² C, LINbus, UART/USART, USB
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	48
Program Memory Size	288KB (288K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 15x12b; D/A 2x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/rochester-electronics/mb9bf564lpmc-g-jne2

Multi-function Serial Interface (Max 6 channels)

- 64 bytes with FIFO (the FIFO step numbers are variable depending on the settings of the communication mode or bit length.)
- Operation mode is selectable from the followings for each channel.
 - UART
 - CSIO
 - LIN
 - I²C
- UART
 - Full-duplex double buffer
 - Selection with or without parity supported
 - Built-in dedicated baud rate generator
 - External clock available as a serial clock
 - Hardware Flow control : Automatically control the transmission by CTS/RTS (only ch.4)
 - Various error detect functions available (parity errors, framing errors, and overrun errors)
- CSIO
 - Full-duplex double buffer
 - Built-in dedicated baud rate generator
 - Overrun error detect function available
 - Serial chip select function (ch.6 only)
 - Supports high-speed SPI (ch.0 and ch.6 only)
 - Data length 5 to 16-bit
- LIN
 - LIN protocol Rev.2.1 supported
 - Full-duplex double buffer
 - Master/Slave mode supported
 - LIN break field generation (can change to 13 to 16-bit length)
 - LIN break delimiter generation (can change to 1 to 4-bit length)
 - Various error detect functions available (parity errors, framing errors, and overrun errors)
- I²C
 - Standard mode (Max 100 kbps) / High-speed mode (Max 400 kbps) supported
 - Fast mode Plus (Fm+) (Max 1000 kbps, only for ch.3=ch.A and ch.4=ch.B) supported

DMA Controller (8 channels)

DMA Controller has an independent bus for CPU, so CPU and DMA Controller can process simultaneously.

- 8 independently configured and operated channels
- Transfer can be started by software or request from the built-in peripherals
- Transfer address area: 32-bit (4 Gbytes)
- Transfer mode: Block transfer/Burst transfer/Demand transfer
- Transfer data type: bytes/half-word/word
- Transfer block count: 1 to 16
- Number of transfers: 1 to 65536

DSTC (Descriptor System data Transfer Controller) (128 channels)

The DSTC can transfer data at high-speed without going via the CPU. The DSTC adopts the Descriptor system and, following the specified contents of the Descriptor which has already been constructed on the memory, can access directly the memory /peripheral device and performs the data transfer operation.

It supports the software activation, the hardware activation and the chain activation functions.

A/D Converter (Max 15 channels) [12-bit A/D Converter]

- Successive Approximation type
- Built-in 2 units
- Conversion time: 0.5 μ s @ 5 V
- Priority conversion available (priority at 2levels)
- Scanning conversion mode
- Built-in FIFO for conversion data storage (for SCAN conversion: 16steps, for Priority conversion: 4steps)

DA Converter (Max 2 channels)

- R-2R type
- 12-bit resolution

Base Timer (Max 8 channels)

Operation mode is selectable from the followings for each channel.

- 16-bit PWM timer
- 16-bit PPG timer
- 16-/32-bit reload timer
- 16-/32-bit PWC timer

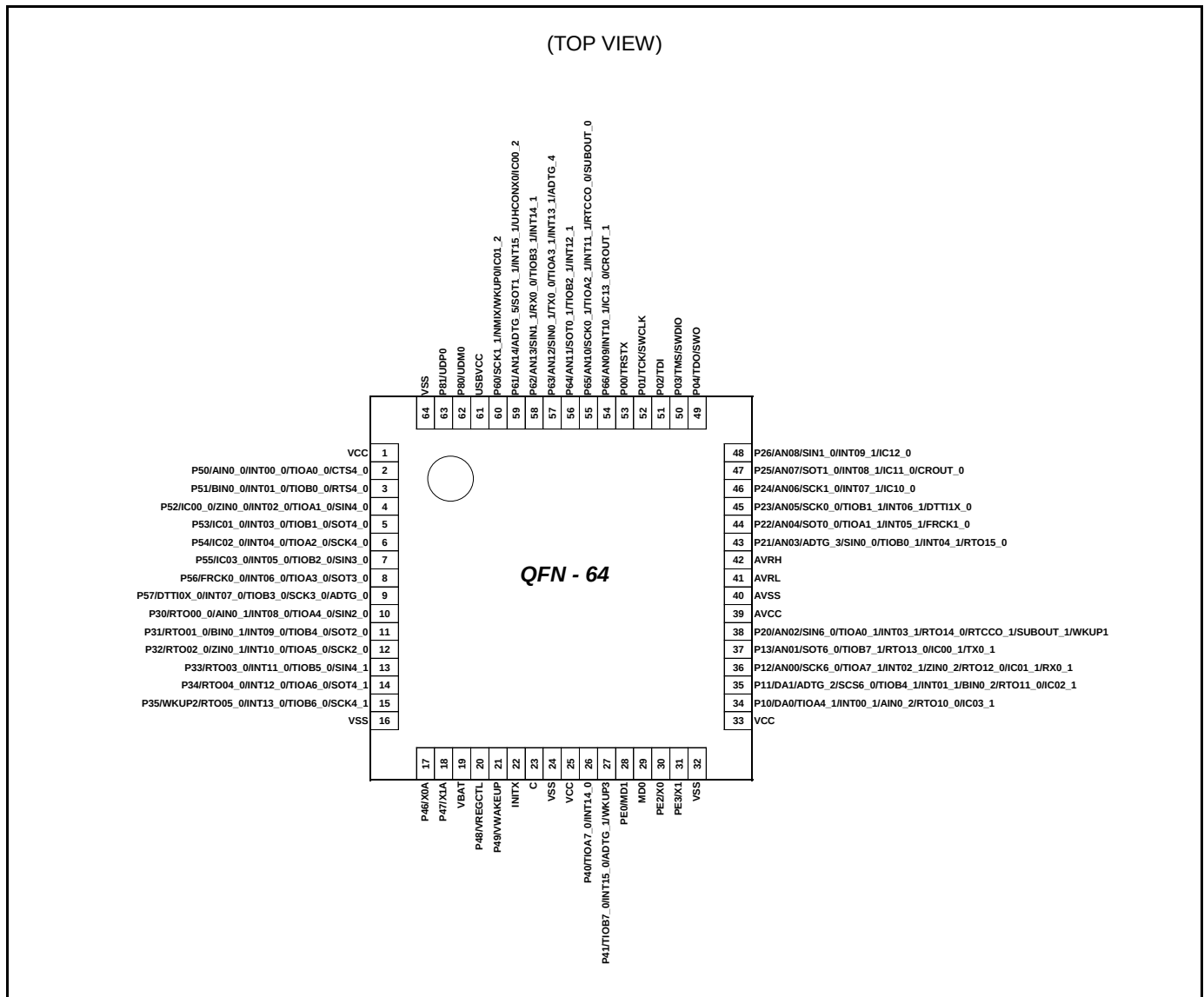
General Purpose I/O Port

This series can use its pins as general purpose I/O ports when they are not used for external bus or peripherals. Moreover, the port relocate function is built in. It can set which I/O port the peripheral function can be allocated.

- Capable of pull-up control per pin
- Capable of reading pin level directly
- Built-in the port relocate function
- Up to 48 high-speed general-purpose I/O ports @ 64 pin Package
- Some pin is 5 V tolerant I/O.
See 4. Pin Description and 5. I/O Circuit Type for the corresponding pins.

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LCC-64P-M24



4. Pin Description

4.1 List of Pin Numbers

The number after the underscore ("_") in pin names such as XXX_1 and XXX_2 indicates the relocated port number. For these pins, there are multiple pins that provide the same function for the same channel. Use the extended port function register (EPFR) to select the pin.

Pin No		Pin Name	I/O circuit type	Pin state type
LQFP64 QFN64	LQFP48 QFN48			
1	1	VCC	-	-
2	-	P50	E	K
		AIN0_0		
		INT00_0		
		TIOA0_0		
		CTS4_0		
3	-	P51	E	K
		BIN0_0		
		INT01_0		
		TIOB0_0		
		RTS4_0		
4	-	P52	I	K
		IC00_0		
		ZIN0_0		
		INT02_0		
		TIOA1_0		
		SIN4_0		
5	-	P53	N	K
		IC01_0		
		INT03_0		
		TIOB1_0		
		SOT4_0 (SDA4_0)		
6	2	P54	N	K
		IC02_0		
		INT04_0		
		TIOA2_0		
	-	SCK4_0 (SCL4_0)		
7	3	P55	I	K
		IC03_0		
		INT05_0		
		TIOB2_0		
		SIN3_0		
8	4	P56	N	K
		FRCK0_0		
		INT06_0		
		TIOA3_0		
		SOT3_0 (SDA3_0)		

Pin function	Pin name	Function description	Pin No	
			LQFP64 QFN64	LQFP48 QFN48
Multi-function Serial 0	SIN0_0	Multi-function serial interface ch.0 input pin	43	34
	SIN0_1		57	-
	SOT0_0 (SDA0_0)	Multi-function serial interface ch.0 output pin. This pin operates as SOT0 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA0 when it is used in an I ² C (operation mode 4).	44	35
	SOT0_1 (SDA0_1)		56	-
	SCK0_0 (SCL0_0)	Multi-function serial interface ch.0 clock I/O pin. This pin operates as SCK0 when it is used in a CSIO (operation modes 2) and as SCL0 when it is used in an I ² C (operation mode 4).	45	36
	SCK0_1 (SCL0_1)		55	-
Multi-function Serial 1	SIN1_0	Multi-function serial interface ch.1 input pin	48	-
	SIN1_1		58	-
	SOT1_0 (SDA1_0)	Multi-function serial interface ch.1 output pin. This pin operates as SOT1 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA1 when it is used in an I ² C (operation mode 4).	47	-
	SOT1_1 (SDA1_1)		59	43
	SCK1_0 (SCL1_0)	Multi-function serial interface ch.1 clock I/O pin. This pin operates as SCK1 when it is used in a CSIO (operation modes 2) and as SCL1 when it is used in an I ² C (operation mode 4).	46	-
	SCK1_1 (SCL1_1)		60	44
Multi-function Serial 2	SIN2_0	Multi-function serial interface ch.2 input pin	10	6
	SOT2_0 (SDA2_0)	Multi-function serial interface ch.2 output pin. This pin operates as SOT2 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA2 when it is used in an I ² C (operation mode 4).	11	7
	SCK2_0 (SCL2_0)	Multi-function serial interface ch.2 clock I/O pin. This pin operates as SCK2 when it is used in a CSIO (operation modes 2) and as SCL2 when it is used in an I ² C (operation mode 4).	12	8

Handling when Using Multi-function Serial Pin as I²C Pin

If it is using the multi-function serial pin as I²C pins, P-ch transistor of digital output is always disabled.

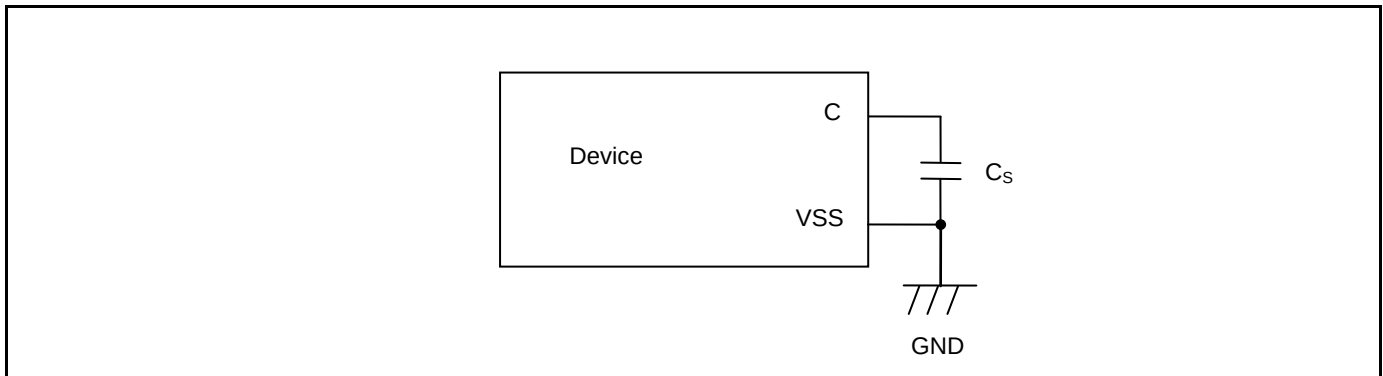
However, I²C pins need to keep the electrical characteristic like other pins and not to connect to the external I²C bus system with power OFF.

C Pin

This series contains the regulator. Be sure to connect a smoothing capacitor (C_S) for the regulator between the C pin and the GND pin. Please use a ceramic capacitor or a capacitor of equivalent frequency characteristics as a smoothing capacitor.

However, some laminated ceramic capacitors have the characteristics of capacitance variation due to thermal fluctuation (F characteristics and Y5V characteristics). Please select the capacitor that meets the specifications in the operating conditions to use by evaluating the temperature characteristics of a capacitor.

A smoothing capacitor of about 4.7 μF would be recommended for this series.



Mode Pins (MD0)

Connect the MD pin (MD0) directly to VCC or VSS pins. Design the printed circuit board such that the pull-up/down resistance stays low, as well as the distance between the mode pins and VCC pins or VSS pins is as short as possible and the connection impedance is low, when the pins are pulled-up/down such as for switching the pin level and rewriting the Flash memory data. It is because of preventing the device erroneously switching to test mode due to noise.

Notes on Power-on

Turn power on/off in the following order or at the same time.

If not using the A/D converter and D/A converter, connect AVCC = VCC and AVSS = VSS.

Turning on: VBAT → VCC → USBVCC

VCC → AVCC → AVRH

Turning off: USBVCC → VCC → VBAT

AVRH → AVCC → VCC

Serial Communication

There is a possibility to receive wrong data due to the noise or other causes on the serial communication.

Therefore, design a printed circuit board so as to avoid noise.

Consider the case of receiving wrong data due to noise, perform error detection such as by applying a checksum of data at the end.

If an error is detected, retransmit the data.

Differences in Features among the Products with Different Memory Sizes and between Flash Products and MASK Products

The electric characteristics including power consumption, ESD, latch-up, noise characteristics, and oscillation characteristics among the products with different memory sizes and between Flash products and MASK products are different because chip layout and memory structures are different.

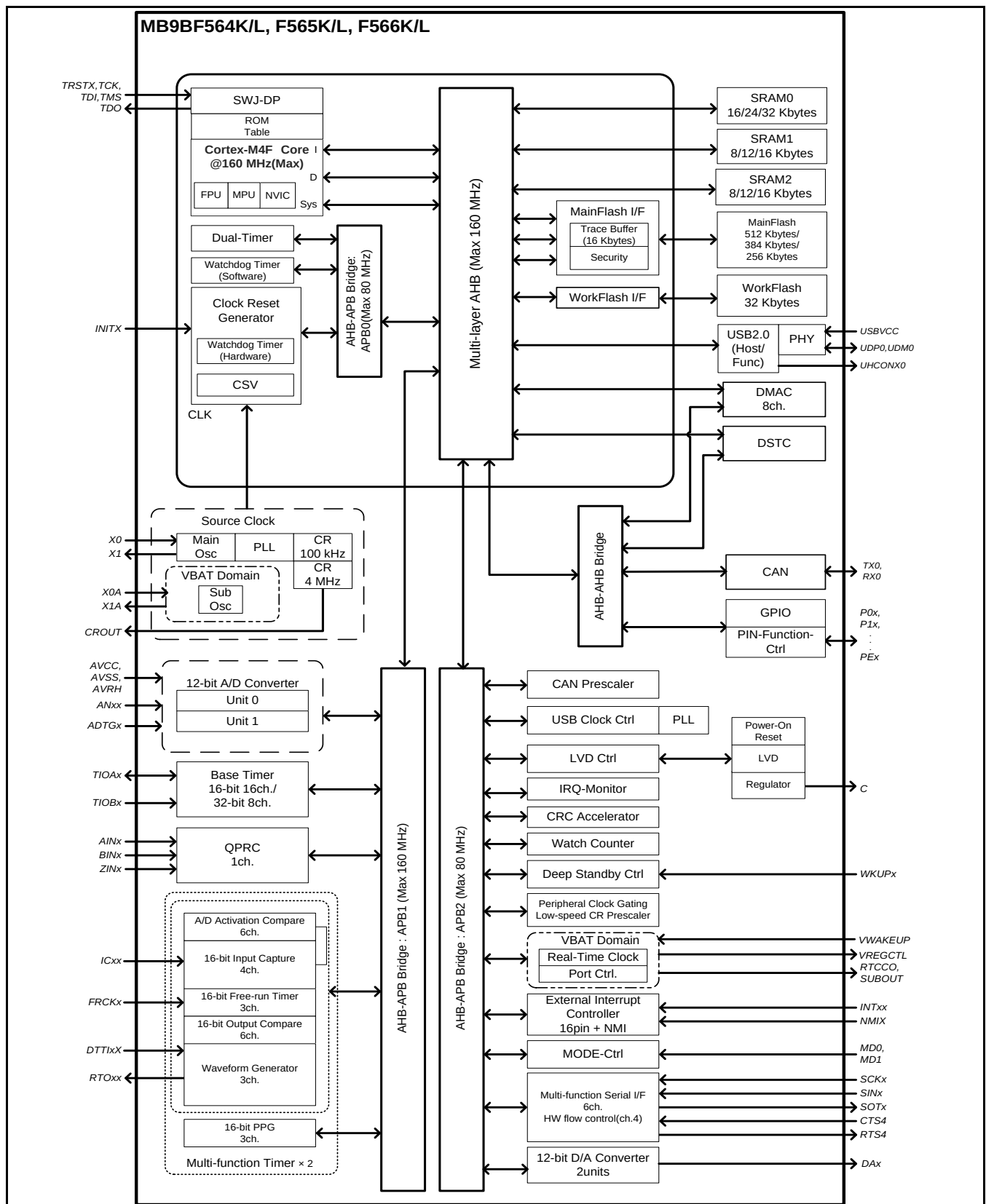
If you are switching to use a different product of the same series, please make sure to evaluate the electric characteristics.

Pull-Up Function of 5 V Tolerant I/O

Please do not input the signal more than VCC voltage at the time of pull-up function use of 5V tolerant I/O.

Handling when Using Debug Pins

When debug pins (TDO/TMS/TDI/TCK/TRSTX or SWO/SWDIO/SWCLK) are set to GPIO or other peripheral functions, only set them as output, do not set them as input.



Peripheral Address Map

Start address	End address	Bus	Peripherals
0x4000_0000	0x4000_0FFF	AHB	MainFlash I/F register
0x4000_1000	0x4000_FFFF		Reserved
0x4001_0000	0x4001_0FFF	APB0	Clock/Reset Control
0x4001_1000	0x4001_1FFF		Hardware Watchdog timer
0x4001_2000	0x4001_2FFF		Software Watchdog timer
0x4001_3000	0x4001_4FFF		Reserved
0x4001_5000	0x4001_5FFF		Dual-Timer
0x4001_6000	0x4001_FFFF		Reserved
0x4002_0000	0x4002_0FFF		Multi-function timer unit0
0x4002_1000	0x4002_1FFF		Multi-function timer unit1
0x4002_2000	0x4003_FFFF	APB1	Reserved
0x4002_4000	0x4002_4FFF		PPG
0x4002_5000	0x4002_5FFF		Base Timer
0x4002_6000	0x4002_6FFF		Quadrature Position/Revolution Counter
0x4002_7000	0x4002_7FFF		A/D Converter
0x4002_8000	0x4002_DFFF		Reserved
0x4002_E000	0x4002_EFFF		Internal CR trimming
0x4002_F000	0x4002_FFFF		Reserved
0x4003_0000	0x4003_0FFF		External Interrupt Controller
0x4003_1000	0x4003_1FFF		Interrupt Request Batch-Read Function
0x4003_2000	0x4003_4FFF		Reserved
0x4003_3000	0x4003_3FFF		D/A Converter
0x4003_4000	0x4003_4FFF	APB2	Reserved
0x4003_5000	0x4003_57FF		Low Voltage Detector
0x4003_5800	0x4003_5FFF		Deep standby mode Controller
0x4003_6000	0x4003_6FFF		USB clock generator
0x4003_7000	0x4003_7FFF		CAN prescaler
0x4003_8000	0x4003_8FFF		Multi-function serial Interface
0x4003_9000	0x4003_9FFF		CRC
0x4003_A000	0x4003_AFFF		Watch Counter
0x4003_B000	0x4003_BFFF		RTC/Port Ctrl
0x4003_C000	0x4003_C0FF		Low-speed CR Prescaler
0x4003_C100	0x4003_C7FF		Peripheral Clock Gating
0x4003_C800	0x4003_FFFF		Reserved
0x4004_0000	0x4004_FFFF	AHB	USB ch.0
0x4005_0000	0x4005_FFFF		Reserved
0x4006_0000	0x4006_0FFF		DMAC register
0x4006_1000	0x4006_1FFF		DSTC register
0x4006_2000	0x4006_2FFF		CAN ch.0
0x4006_3000	0x4006_EFFF		Reserved
0x4006_F000	0x4006_FFFF		GPIO
0x4006_7000	0x41FF_FFFF		Reserved
0x200E_0000	0x200E_FFFF		WorkFlash I/F register

Parameter	Symbol	Pin Name	Conditions	Frequency* ⁴ (MHz)	Value		Unit	Remarks
					Typ* ¹	Max* ²		
Power supply current	I _{CC}	VCC	Normal operation (PLL)	*5	72 MHz	41	75	mA *3 When all peripheral clocks are ON
					60 MHz	36	69	
					48 MHz	31	64	
					36 MHz	25	57	
					24 MHz	18	50	
					12 MHz	11	42	
					8 MHz	8.1	39	
					4 MHz	5.4	37	
					72 MHz	32	63	mA *3 When all peripheral clocks are OFF
					60 MHz	28	58	
					48 MHz	24	54	
					36 MHz	20	50	
					24 MHz	15	45	
					12 MHz	9.1	38	
					8 MHz	6.9	36	
					4 MHz	4.6	34	

*1: T_A=+25 °C, V_{CC}=3.3 V

*2: T_j=+125 °C, V_{CC}=5.5 V

*3: When all ports are fixed.

*4: Frequency is a value of HCLK. PCLK0=PCLK1=PCLK2=HCLK

*5: When 0 wait-cycle mode (FRWTR.RWT = 00, FSYNDN.SD = 00)

Parameter	Symbol	Pin Name	Conditions	Frequency* ⁴	Value		Unit	Remarks
					Typ* ¹	Max* ²		
Power supply current	I _{CC}	VCC	Normal operation (built-in high-speed CR)	*5 4 MHz	3.3	29	mA	*3 When all peripheral clocks are ON
					2.8	29	mA	*3 When all peripheral clocks are OFF
			Normal operation (sub oscillation)	*5 32 kHz	0.51	27	mA	*3 When all peripheral clocks are ON
					0.50	27	mA	*3 When all peripheral clocks are OFF
			Normal operation (built-in low-speed CR)	*5 100 kHz	0.54	27	mA	*3 When all peripheral clocks are ON
					0.52	27	mA	*3 When all peripheral clocks are OFF

*1: T_A=+25 °C, V_{CC}=3.3 V

*2: T_j=+125 °C, V_{CC}=5.5 V

*3: When all ports are fixed.

*4: Frequency is a value of HCLK. PCLK0=PCLK1=PCLK2=HCLK/2

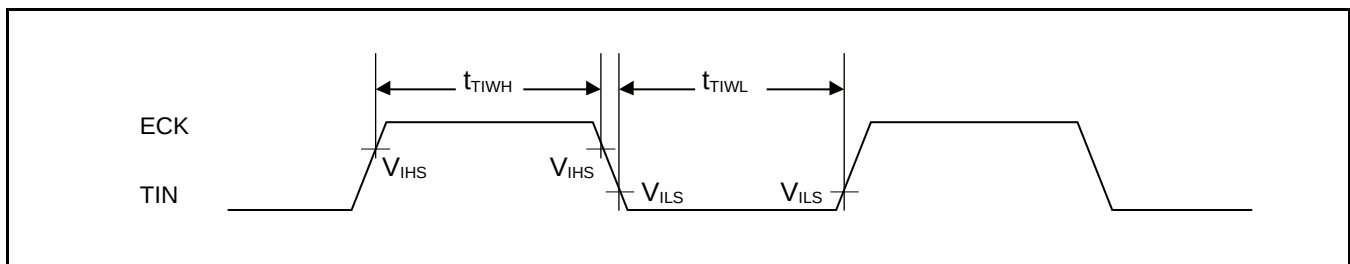
*5: When 0 wait-cycle mode (FRWTR.RWT = 00, FSYNDN.SD = 000)

12.4.10 Base Timer Input Timing

Timer Input Timing

($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$)

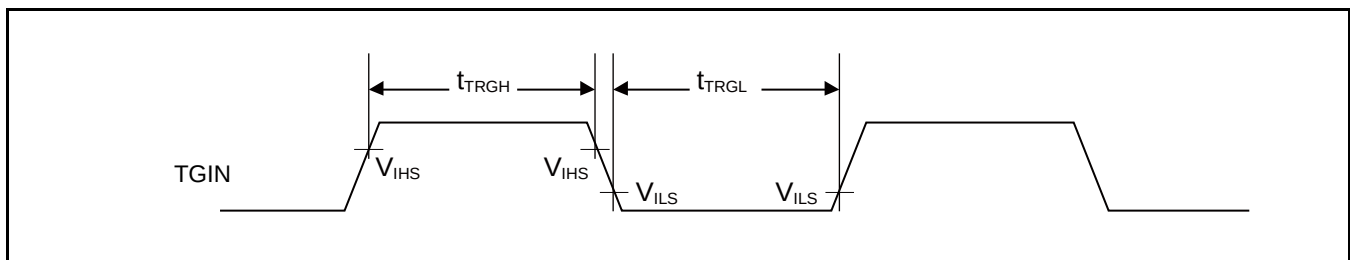
Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{TIWH} , t_{TIWL}	TIOAn/TIOBn (when using as ECK, TIN)	-	$2t_{CYCP}$	-	ns	



Trigger Input Timing

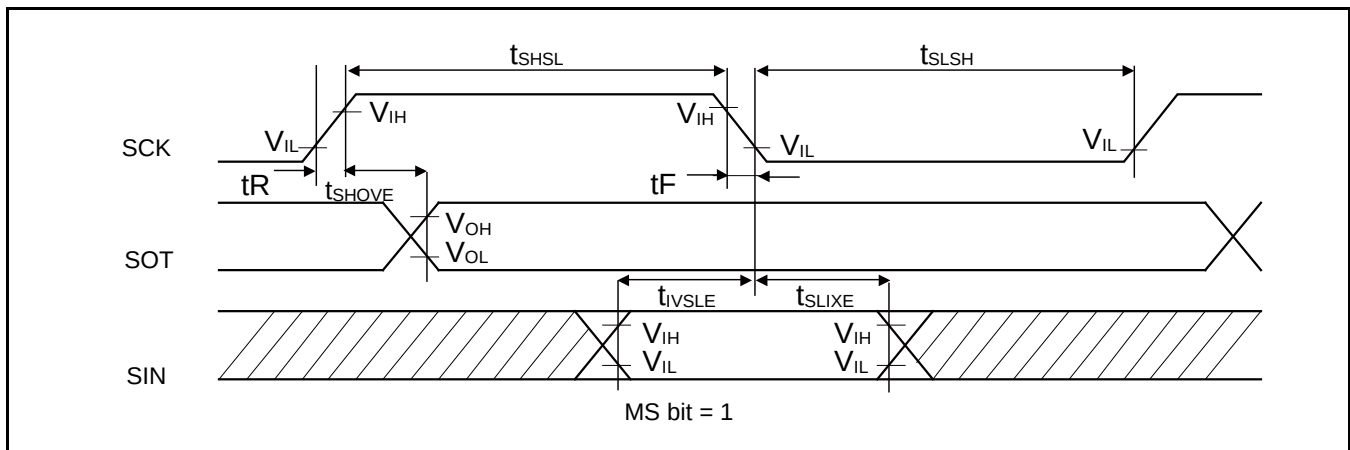
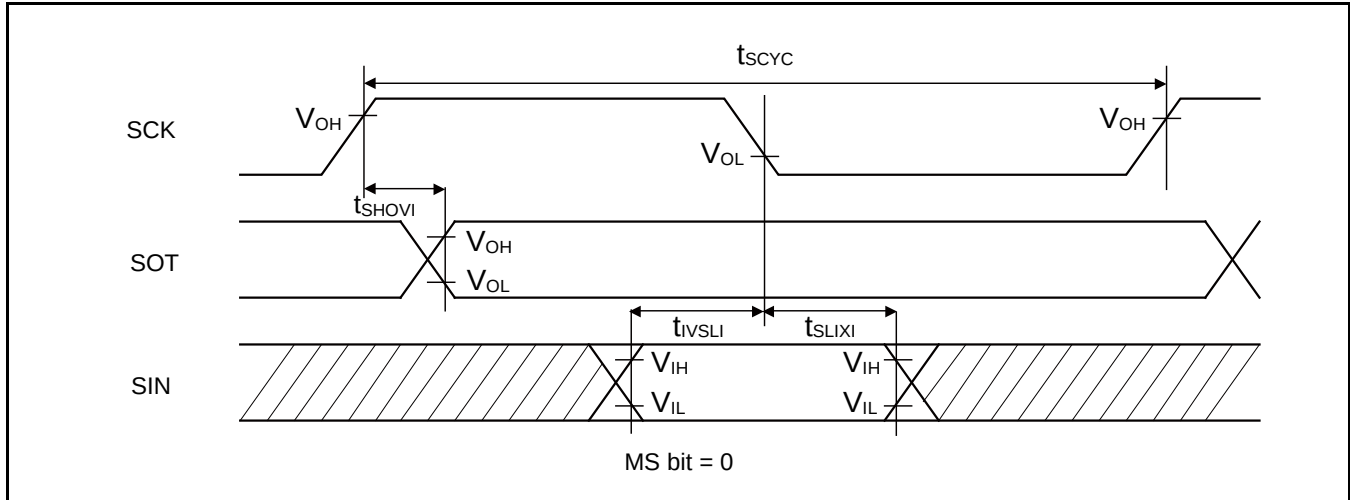
($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{TRGH} , t_{TRGL}	TIOAn/TIOBn (when using as TGIN)	-	$2t_{CYCP}$	-	ns	



Note:

- t_{CYCP} indicates the APB bus clock cycle time.
About the APB bus number which the Base Timer is connected to, see 8. Block Diagram in this data sheet.



Synchronous Serial (SPI = 1, SCINV = 1)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	V _{CC} < 4.5 V		V _{CC} ≥ 4.5 V		Unit
				Min	Max	Min	Max	
Serial clock cycle time	t _{SCYC}	SCKx	Internal shift clock operation	4t _{CYCP}	-	4t _{CYCP}	-	ns
SCK↓→SOT delay time	t _{SLOVI}	SCKx, SOTx		- 30	+ 30	- 20	+ 20	ns
SIN→SCK↑ setup time	t _{IVSHI}	SCKx, SINx		50	-	30	-	ns
SCK↑→SIN hold time	t _{SHIXI}	SCKx, SINx		0	-	0	-	ns
SOT→SCK↑ delay time	t _{SOVHI}	SCKx, SOTx		2t _{CYCP} - 30	-	2t _{CYCP} - 30	-	ns
Serial clock "L" pulse width	t _{SLSH}	SCKx	External shift clock operation	2t _{CYCP} - 10	-	2t _{CYCP} - 10	-	ns
Serial clock "H" pulse width	t _{SHSL}	SCKx		t _{CYCP} + 10	-	t _{CYCP} + 10	-	ns
SCK↓→SOT delay time	t _{SLOVE}	SCKx, SOTx		-	50	-	30	ns
SIN→SCK↑ setup time	t _{IVSHE}	SCKx, SINx		10	-	10	-	ns
SCK↑→SIN hold time	t _{SHIXE}	SCKx, SINx		20	-	20	-	ns
SCK falling time	t _F	SCKx		-	5	-	5	ns
SCK rising time	t _R	SCKx		-	5	-	5	ns

Notes:

- The above characteristics apply to CLK synchronous mode.
- t_{CYCP} indicates the APB bus clock cycle time.
About the APB bus number which UART is connected to, see 8. Block Diagram in this data sheet.
- These characteristics only guarantee the same relocate port number.
For example, the combination of SCLKx_0 and SOTx_1 is not guaranteed.
- When the external load capacitance C_L = 30 pF.

High-speed Synchronous Serial (SPI = 0, SCINV = 0)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	V _{CC} < 4.5V		V _{CC} ≥ 4.5V		Unit
				Min	Max	Min	Max	
Serial clock cycle time	t _{SCYC}	SCKx	Internal shift clock operation	4t _{CYCP}	-	4t _{CYCP}	-	ns
SCK↓→SOT delay time	t _{SLOVI}	SCKx, SOTx		-10	+10	-10	+10	ns
SIN→SCK↑ setup time	t _{IVSHI}	SCKx, SINx		14	-	12.5	-	ns
				12.5*				
SCK↑→SIN hold time	t _{SHIXI}	SCKx, SINx		5	-	5	-	ns
Serial clock "L" pulse width	t _{SLSH}	SCKx	External shift clock operation	2t _{CYCP} – 5	-	2t _{CYCP} – 5	-	ns
Serial clock "H" pulse width	t _{SHSL}	SCKx		t _{CYCP} + 10	-	t _{CYCP} + 10	-	ns
SCK↓→SOT delay time	t _{SLOVE}	SCKx, SOTx		-	15	-	15	ns
SIN→SCK↑ setup time	t _{IVSHE}	SCKx, SINx		5	-	5	-	ns
SCK↑→SIN hold time	t _{SHIXE}	SCKx,		5	-	5	-	ns
		SINx						
SCK falling time	tF	SCKx		-	5	-	5	ns
SCK rising time	tR	SCKx		-	5	-	5	ns

Notes:

- The above characteristics apply to CLK synchronous mode.
- t_{CYCP} indicates the APB bus clock cycle time.
About the APB bus number which UART is connected to, see 8. Block Diagram in this data sheet.
- These characteristics only guarantee the following pins.
 - No chip select: SIN0_1, SOT0_1, SCK0_1
 - Chip select: SIN6_0, SOT6_0, SCK6_0, SCS6_0
- When the external load capacitance C_L = 30 pF. (For *, when C_L = 10 pF)

When Using High-speed Synchronous Serial Chip Select (SPI = 1, SCINV = 0, MS=0, CSLVL=1)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Conditions	V _{CC} < 4.5 V		V _{CC} ≥ 4.5 V		Unit
			Min	Max	Min	Max	
SCS↓→SCK↓setup time	t _{CSSI}	Internal shift clock operation	(*1)-20	(*1)+0	(*1)-20	(*1)+0	ns
SCK↑→SCS↑ hold time	t _{CShI}		(*2)+0	(*2)+20	(*2)+0	(*2)+20	ns
SCS deselect time	t _{CSDI}		(*3)-20+5t _{CYCP}	(*3)+20+5t _{CYCP}	(*3)-20+5t _{CYCP}	(*3)+20+5t _{CYCP}	ns
SCS↓→SCK↓setup time	t _{CSSe}	External shift clock operation	3t _{CYCP} +15	-	3t _{CYCP} +15	-	ns
SCK↑→SCS↑ hold time	t _{CShE}		0	-	0	-	ns
SCS deselect time	t _{CSDe}		3t _{CYCP} +15	-	3t _{CYCP} +15	-	ns
SCS↓→SOT delay time	t _{DSE}		-	25	-	25	ns
SCS↑→SOT delay time	t _{DEE}		0	-	0	-	ns

(*1): CSSU bit value×serial chip select timing operating clock cycle [ns]

(*2): CSHD bit value×serial chip select timing operating clock cycle [ns]

(*3): CSDS bit value×serial chip select timing operating clock cycle [ns]

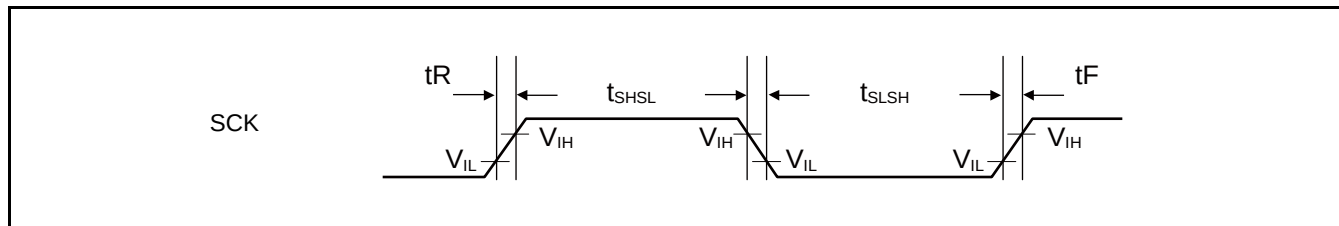
Notes:

- t_{CYCP} indicates the APB bus clock cycle time.
About the APB bus number which UART is connected to, see 8. Block Diagram in this data sheet.
- About CSSU, CSHD, CSDS, serial chip select timing operating clock, see FM4 Family Peripheral Manual.
- When the external load capacitance C_L = 30 pF.

External Clock (EXT = 1): when in Asynchronous Mode Only

($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$)

Parameter	Symbol	Condition	Value		Unit	Remarks
			Min	Max		
Serial clock "L" pulse width	t_{SLSH}	$C_L = 30 \text{ pF}$	$t_{CYCP} + 10$	-	ns	
Serial clock "H" pulse width	t_{SHSL}		$t_{CYCP} + 10$	-	ns	
SCK falling time	t_F		-	5	ns	
SCK rising time	t_R		-	5	ns	



12.4.14 I²C Timing

Typical Mode, High-speed Mode

 (V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Conditions	Typical Mode		High-speed Mode		Unit	Remarks
			Min	Max	Min	Max		
SCL clock frequency	F _{SCL}	C _L = 30 pF, R = (V _p /I _{OL})* ¹	0	100	0	400	kHz	
(Repeated) START condition hold time SDA ↓ → SCL ↓	t _{HDSTA}		4.0	-	0.6	-	μs	
SCL clock "L" width	t _{LOW}		4.7	-	1.3	-	μs	
SCL clock "H" width	t _{HIGH}		4.0	-	0.6	-	μs	
(Repeated) START condition setup time SCL ↑ → SDA ↓	t _{SUSTA}		4.7	-	0.6	-	μs	
Data hold time SCL ↓ → SDA ↓ ↑	t _{HDDAT}		0	3.45* ²	0	0.9* ³	μs	
Data setup time SDA ↓ ↑ → SCL ↑	t _{SUDAT}		250	-	100	-	ns	
STOP condition setup time SCL ↑ → SDA ↑	t _{SUSTO}		4.0	-	0.6	-	μs	
Bus free time between "STOP condition" and "START condition"	t _{BUF}		4.7	-	1.3	-	μs	
Noise filter	t _{SP}	2 MHz ≤ t _{CYCP} < 40 MHz	2t _{CYCP} * ⁴	-	2t _{CYCP} * ⁴	-	ns	*5
		40 MHz ≤ t _{CYCP} < 60 MHz	4t _{CYCP} * ⁴	-	4t _{CYCP} * ⁴	-	ns	
		60 MHz ≤ t _{CYCP} < 80 MHz	6t _{CYCP} * ⁴	-	6t _{CYCP} * ⁴	-	ns	
		80 MHz ≤ t _{CYCP} < 100 MHz	8t _{CYCP} * ⁴	-	8t _{CYCP} * ⁴	-	ns	
		100 MHz ≤ t _{CYCP} < 120 MHz	10t _{CYCP} * ⁴	-	10t _{CYCP} * ⁴	-	ns	
		120 MHz ≤ t _{CYCP} < 140 MHz	12t _{CYCP} * ⁴	-	12t _{CYCP} * ⁴	-	ns	
		140 MHz ≤ t _{CYCP} < 160 MHz	14t _{CYCP} * ⁴	-	14t _{CYCP} * ⁴	-	ns	
		160 MHz ≤ t _{CYCP} < 180 MHz	16t _{CYCP} * ⁴	-	16t _{CYCP} * ⁴	-	ns	

*1: R and C_L represent the pull-up resistance and load capacitance of the SCL and SDA lines, respectively. V_p indicates the power supply voltage of the pull-up resistance and I_{OL} indicates V_{OL} guaranteed current.

*2: The maximum t_{HDDAT} must satisfy that it does not extend at least "L" period (t_{LOW}) of device's SCL signal.

*3: A high-speed mode I²C bus device can be used on a typical mode I²C bus system as long as the device satisfies the requirement of t_{SUDAT} ≥ 250 ns.

*4: t_{CYCP} is the APB bus clock cycle time.

About the APB bus number that I²C is connected to, see "8. Block Diagram" in this data sheet.

*5: The noise filter time can be changed by register settings.

Change the number of the noise filter steps according to APB bus clock frequency.

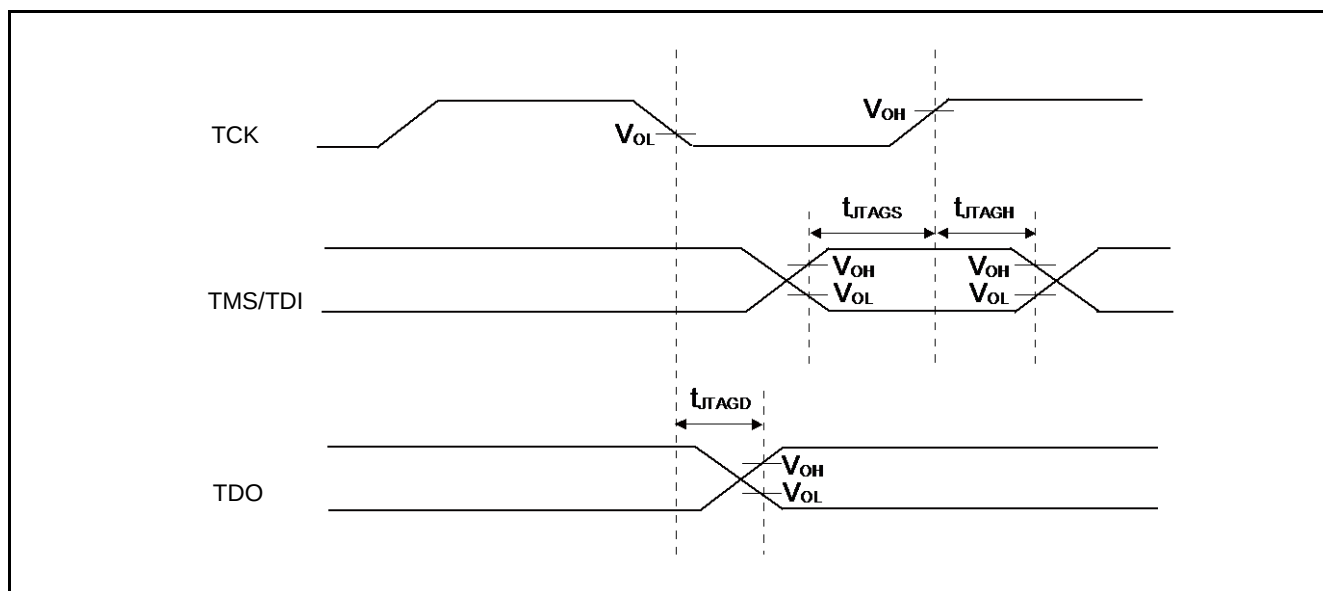
12.4.15 JTAG Timing

($V_{CC} = 2.7V$ to $5.5V$, $V_{SS} = 0V$)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
TMS, TDI setup time	t_{JTAGS}	TCK, TMS, TDI	$V_{CC} \geq 4.5 V$	15	-	ns	
			$V_{CC} < 4.5 V$				
TMS, TDI hold time	t_{JTAGH}	TCK, TMS, TDI	$V_{CC} \geq 4.5 V$	15	-	ns	
			$V_{CC} < 4.5 V$				
TDO delay time	t_{JTAGD}	TCK, TDO	$V_{CC} \geq 4.5 V$	-	25	ns	
			$V_{CC} < 4.5 V$	-	45		

Note:

- When the external load capacitance $C_L = 30 pF$.



12.8 Low-Voltage Detection Characteristics

12.8.1 Low-Voltage Detection Reset

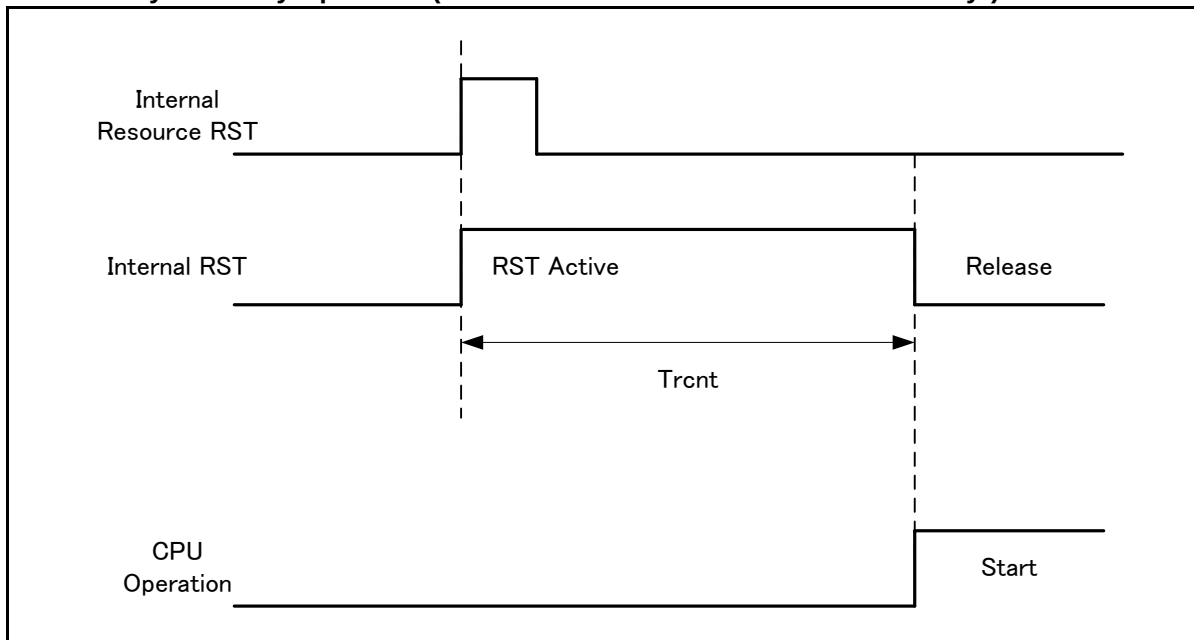
Parameter	Symbol	Conditions	Value			Unit	Remarks
			Min	Typ	Max		
Detected voltage	VDL	-	2.25	2.45	2.65	V	When voltage drops
Released voltage	VDH	-	2.30	2.50	2.70	V	When voltage rises

12.8.2 Interrupt of Low-Voltage Detection

Parameter	Symbol	Conditions	Value			Unit	Remarks
			Min	Typ	Max		
Detected voltage	VDL	SVHI = 00111	2.58	2.8	3.02	V	When voltage drops
Released voltage	VDH		2.67	2.9	3.13	V	When voltage rises
Detected voltage	VDL	SVHI = 00100	2.76	3.0	3.24	V	When voltage drops
Released voltage	VDH		2.85	3.1	3.34	V	When voltage rises
Detected voltage	VDL	SVHI = 01100	2.94	3.2	3.45	V	When voltage drops
Released voltage	VDH		3.04	3.3	3.56	V	When voltage rises
Detected voltage	VDL	SVHI = 01111	3.31	3.6	3.88	V	When voltage drops
Released voltage	VDH		3.40	3.7	3.99	V	When voltage rises
Detected voltage	VDL	SVHI = 01110	3.40	3.7	3.99	V	When voltage drops
Released voltage	VDH		3.50	3.8	4.10	V	When voltage rises
Detected voltage	VDL	SVHI = 01001	3.68	4.0	4.32	V	When voltage drops
Released voltage	VDH		3.77	4.1	4.42	V	When voltage rises
Detected voltage	VDL	SVHI = 01000	3.77	4.1	4.42	V	When voltage drops
Released voltage	VDH		3.86	4.2	4.53	V	When voltage rises
Detected voltage	VDL	SVHI = 11000	3.86	4.2	4.53	V	When voltage drops
Released voltage	VDH		3.96	4.3	4.64	V	When voltage rises
LVD stabilization wait time	T _{LVDW}	-	-	-	4480× t _{CYCP} *	μs	

*: t_{CYCP} indicates the APB2 bus clock cycle time.

Example of Standby Recovery Operation (when in Internal Resource Reset Recovery*)

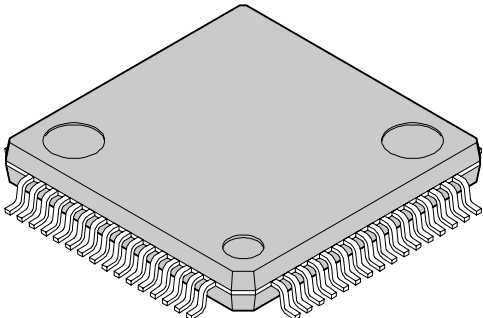


*: Depending on the standby mode, the reset issue from the internal resource is not included in the recovery cause.

Notes:

- The return factor is different in each Low-Power consumption modes.
See CHAPTER 6: Low Power Consumption Mode and Operations of Standby Modes in FM4 Family Peripheral Manual Main part (002-04856).
- The time during the power-on reset/low-voltage detection reset is excluded to the recovery source. See (6) Power-on Reset Timing in 12.4 AC Characteristics in 12. Electrical Characteristics for the detail on the time during the power-on reset/low-voltage detection reset.
- When in recovery from reset, CPU changes to the high-speed CR run mode. When using the main clock or the PLL clock, it is necessary to add the main clock oscillation stabilization wait time or the main PLL clock stabilization wait time.
- The internal resource reset means the watchdog reset and the CSV reset.

14. Package Dimensions

64-pin plastic LQFP  (FPT-64P-M38)	Lead pitch	0.50 mm
	Package width × package length	10.00 mm × 10.00 mm
	Lead shape	Gullwing
	Lead bend direction	Normal bend
	Sealing method	Plastic mold
	Mounting height	1.70 mm MAX
	Weight	0.32 g

